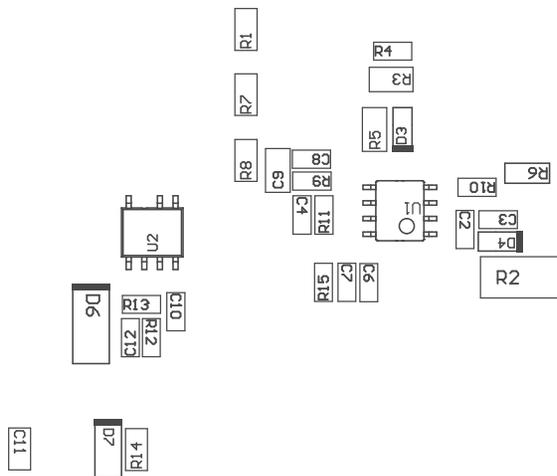


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: TIDA-00776	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-00776		
PLOT NAME = Top Assembly Drawing	GENERATED : 11/17/2016 15:33:10		TEXAS INSTRUMENTS

H6

H5



H8

H7

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00776	REV: E1	SUN REV: Not In VersionControl
	TID #: TIDA-00776		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11/17/2016 15:33:10		TEXAS INSTRUMENTS

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